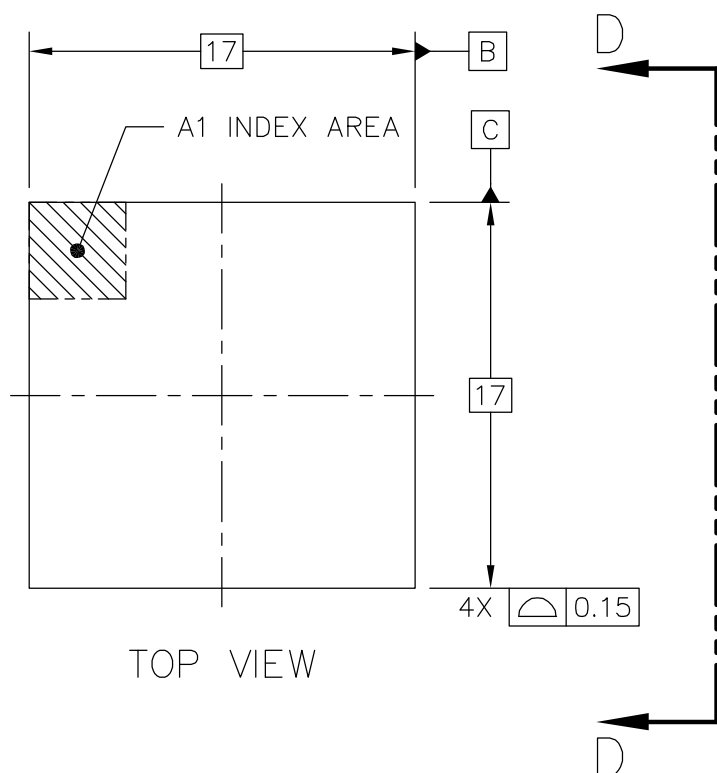
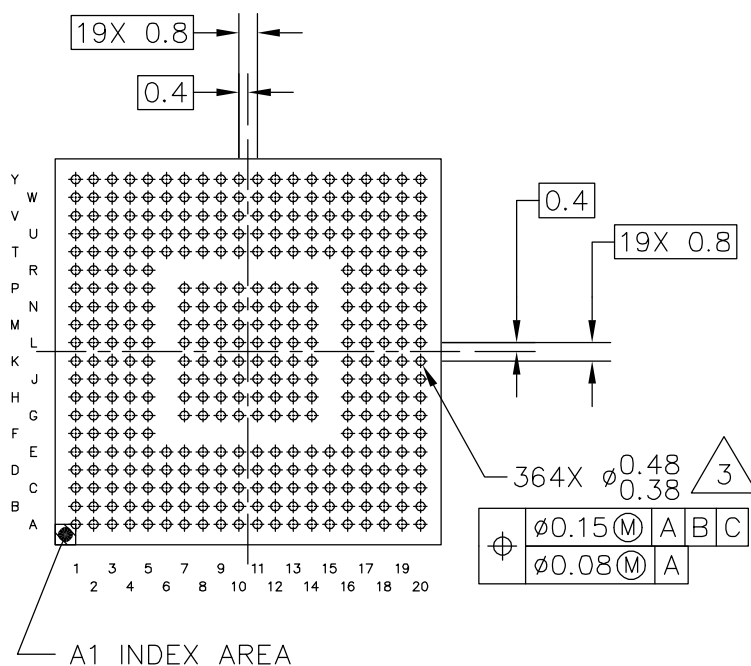
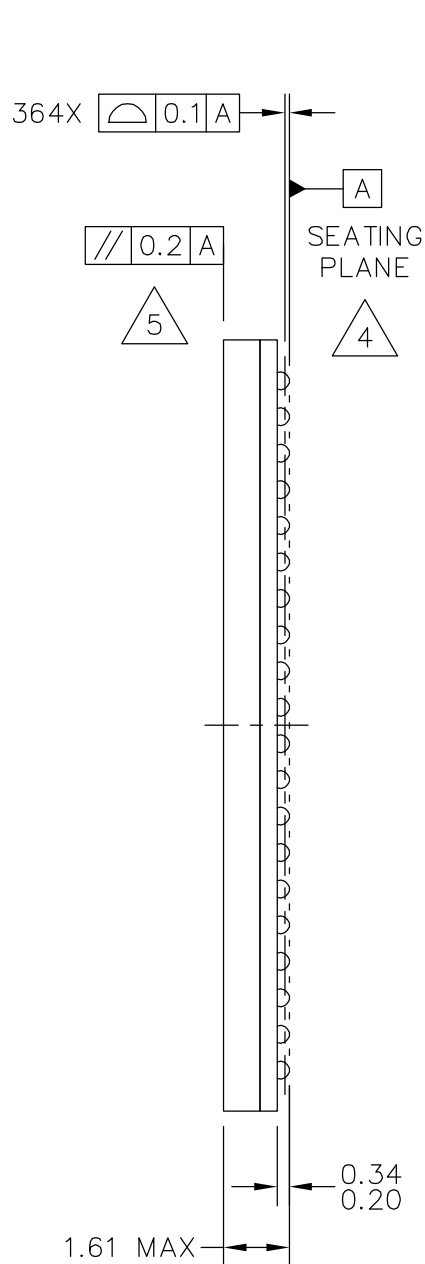




TOP VIEW



BOTTOM VIEW



VIEW D-D

|                                                                |                                 |                            |
|----------------------------------------------------------------|---------------------------------|----------------------------|
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| TITLE: MAPBGA,<br>17 X 17 X 1.45 PKG,<br>0.8 MM PITCH, 364 I/O | DOCUMENT NO: 98ASA00936D REV: A |                            |
|                                                                | STANDARD: NON JEDEC             |                            |
|                                                                | SOT1517-3                       | 10 JUN 2016                |



NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

|                                                                |                           |                            |
|----------------------------------------------------------------|---------------------------|----------------------------|
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| TITLE: MAPBGA,<br>17 X 17 X 1.45 PKG,<br>0.8 MM PITCH, 364 I/O | DOCUMENT NO: 98ASA00936D  | REV: A                     |
|                                                                | STANDARD: NON JEDEC       |                            |
|                                                                | SOT1517–3                 | 10 JUN 2016                |